

Title (en)  
PROCESS FOR PREPARING ELECTROCONDUCTIVE COATINGS

Title (de)  
PROZESS ZUR HERSTELLUNG VON LEITFÄHIGEN BESCHICHTUNGEN

Title (fr)  
PROCESSUS DE PREPARATION DE REVETEMENTS ELECTROCONDUCTEURS

Publication  
**EP 1639607 A1 20060329 (EN)**

Application  
**EP 04741766 A 20040609**

Priority

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Abstract (en)  
[origin: WO2004114326A1] An aqueous dispersion of latex particles, said latex particles containing a polymer containing monomer units according to formula (I), in which R<1> and R<2> independently of one another represent hydrogen or a C1-5-alkyl group or together form an optionally substituted C1-5-alkylene residue and at least one polyanion compound, said latex having a primary particle size of less than 40 nm and said dispersion contains an organic compound containing a diol polyhydroxy- and/or carboxy groups or amide or lactam group or an aprotic compound with a dielectric constant,  $\epsilon$ ,  $\geq 15$ , characterized in that said latex particles contain said at least one polyanion compound and said polymer in a weight ratio of at least 4; a process for preparing an electroconductive coating comprising the steps of: preparing an aqueous solution or dispersion of the abovementioned polymer by polymerization with an initiator in a reaction medium in the presence of at least one polyanion compound under oxidizing or reducing conditions.

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**H01B 1/12; C09D 5/24**

IPC 8 full level  
**C09D 5/24** (2006.01)

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